



Customer Information Notification

202002025I

Issue Date: 23-Feb-2020

Effective Date: 24-Feb-2020

Dear *Product Change Notices Newark*,

Here's your personalized quality information concerning products Newark purchased from NXP. For detailed information we invite you to [view this notification online](#)

This notice is NXP Company Proprietary.



Change Category

- | | | | | |
|--|---|--|---|---|
| <input type="checkbox"/> Wafer Fab Process | <input type="checkbox"/> Assembly Process | <input type="checkbox"/> Product Marking | <input type="checkbox"/> Test Location | <input type="checkbox"/> Design |
| <input type="checkbox"/> Wafer Fab Materials | <input type="checkbox"/> Assembly Materials | <input type="checkbox"/> Mechanical Specification | <input type="checkbox"/> Test Process | <input type="checkbox"/> Errata |
| <input type="checkbox"/> Wafer Fab Location | <input type="checkbox"/> Assembly Location | <input type="checkbox"/> Packing/Shipping/Labeling | <input type="checkbox"/> Test Equipment | <input type="checkbox"/> Electrical spec./Test coverage |
| <input type="checkbox"/> Firmware | <input checked="" type="checkbox"/> Other - Data Sheet Update - Clarification | | | |

MC33926 Data Sheet Update to Rev 16 (28-pin HVQFN Clarifications)

Description

NXP Semiconductors announces the data sheet update to revision 16 for the MC33926 devices associated with this notification. The revision history included in the updated document provides a detailed description of the changes. Changes are summarized below.

Data Sheet Changes:

- Figure 4: updated 28-pin HVQFN pin configuration to indicate four corner pads as AGND
- Section 13.1: added 28-pin HVQFN solder mask information

** Documentation change only for customer clarification - absolutely no changes to the device / product **

New MC33926 revision 16 data sheet is attached to this notice, and can be found at:

<https://www.nxp.com/docs/en/data-sheet/MC33926.pdf>

Corresponding ZVEI Delta Qualification Matrix ID: SEM-DS-02

Reason

The data sheet has been updated to provide additional technical clarification regarding 28-pin HVQFN corner pad labels, and solder mask diagram.

Identification of Affected Products

Product identification does not change

Anticipated Impact on Form, Fit, Function, Reliability or Quality

No impact on form, fit, function, reliability or quality.

Data Sheet Revision

A new datasheet will be issued

Additional information

Affected products and sales history information: see attached file

Additional documents: [view online](#)



Contact and Support

For all inquiries regarding the ePCN tool application or access issues, please [contact NXP "Global Quality Support Team"](#).

For all Quality Notification content inquiries, please contact your local NXP Sales Support team.

For specific questions on this notice or the products affected please contact our specialist directly:

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